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UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

SUGATANI, Shinji, et al.

Group Art Unit: 2814

Serial No.: 10/634,839

Examiner: Howard Weiss

Filed: August 6, 2003

P.T.O. Confirmation No.: 8605

For: MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND
SEMICONDUCTOR CHIP USING SOI SUBSTRATE, FACILITATING
CLEAVING (*as amended*)

AMENDMENT UNDER 37 CFR §1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

July 16, 2004

Sir:

In response to the Office Action dated **April 16, 2004**, entry of the following amendments and remarks, and reconsideration and further examination, are respectfully requested.

Amendments to the Title begin on page 2 of this paper.

Amendments to the Specification begin on page 3 of this paper.

Remarks/Arguments begin on page 4 of this paper.

AMENDMENTS TO THE TITLE:

Amend the title to read as follows:

MANUFACTURING METHOD OF SEMICONDUCTOR DEVICE AND
SEMICONDUCTOR CHIP USING SOI SUBSTRATE, FACILITATING CLEAVING